

**DLP240-24-1**

**RELIABILITY DATA**

DWG No. CA736-57-01			
QA APPD	APPD	CHK	DWG
Jmurray 4/Jun/03	Kath 30-May. 2003	Roger 14/May/03	John 14/May/03

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※ The above data is typical value. As all units have nearly the same characteristics, the data to be considered as ability value.

**1. CALCULATED VALUES OF MTBF****MODEL : DLP240-24-1****(1) Calculating method**

Calculated based on part count reliability projection of JEITA (RCR-9102).

Individual failure rates  $\lambda_G$  is given to each part and MTBF is calculated by the count of each part.

&lt;Formula&gt; :

$$\text{MTBF} = \frac{1}{\lambda_{\text{equip}}} = \frac{1}{\sum_{i=1}^n N_i (\lambda_G \pi_Q)_i} \times 10^6 \text{ (Hours)}$$

 $\lambda_{\text{equip}}$  : Total Equipment Failure Rate (Failure/ $10^6$  Hours) $\lambda_G$  : Generic Failure Rate for The ith Generic Part (Failure/ $10^6$  Hours) $N_i$  : Quantity of ith Generic Part $n$  : Number of Different Generic Part Categories $\pi_Q$  : Generic Quality Factor for The ith Generic Part ( $\pi_Q = 1$ )**(2) MTBF Values** $G_F$  : (Ground , Fixed)**MTBF = 338,446 (Hours)**

## 2. COMPONENT DERATING

**MODEL : DLP240-24-1**

### (1) Calculating Method

#### (a) Measuring Conditions

Input	: 100VAC	• Ambient temperature	: 50°C
Output	: 24V 10.0A(100%)	• Mounting method	: Standard Mounting

#### (b) Semiconductors

Compared with maximum junction temperature and actual one which is calculated based on case temperature, power dissipation and thermal impedance.

#### (c) IC, Resistors, Capacitors, etc.

Ambient temperature, operating condition, power dissipation and so on are within derating criteria.

#### (d) Calculating Method of Thermal Impedance

$$\theta_{j-c} = \frac{T_{j(max)} - T_c}{P_{c(max)}} \quad \theta_{j-a} = \frac{T_{j(max)} - T_a}{P_{c(max)}} \quad \theta_{j-l} = \frac{T_{j(max)} - T_l}{P_{c(max)}}$$

$T_c$  : Case Temperature at Start Point of Derating ; 25°C in General

$T_a$  : Ambient Temperature at Start Point of Derating ; 25°C in General

$T_l$  : Lead Temperature at Start Point of Derating ; 25°C in General

$P_{c(max)}$   
( $P_{ch(max)}$ ) : Maximum Collector(channel) Dissipation

$T_{j(max)}$   
( $T_{ch(max)}$ ) : Maximum Junction(channel) Temperature

$\theta_{j-c}$   
( $\theta_{ch-c}$ ) : Thermal Impedance between Junction(channel) and Case

$\theta_{j-a}$  : Thermal Impedance between Junction and Air

$\theta_{j-l}$  : Thermal Impedance between Junction and Lead

## (2) Component Derating List

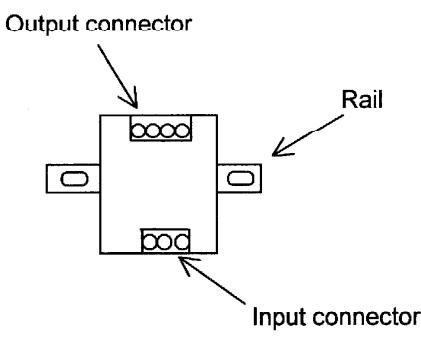
Location No.	$V_{in} = 100VAC$	Load = 100%	$T_a = 50^{\circ}C$
Q1 2SK2837 TOSHIBA	$T_{chmax} = 150^{\circ}C$ , $P_{ch} = 10.47 W$ , $T_{ch} = T_c + ((\theta_{ch-c}) \times P_{ch}) = 117.3^{\circ}C$ $D.F. = 78.2\%$	$\theta_{ch-c} = 0.833^{\circ}C/W$ , $\Delta T_c = 58.6^{\circ}C$	$P_{ch(max)} = 150 W$ , $T_c = 108.6^{\circ}C$
Q2 2SK2611 TOSHIBA	$T_{chmax} = 150^{\circ}C$ , $P_{ch} = 11.13 W$ , $T_{ch} = T_c + ((\theta_{ch-c}) \times P_{ch}) = 119.9^{\circ}C$ $D.F. = 79.9\%$	$\theta_{ch-c} = 0.833^{\circ}C/W$ , $\Delta T_c = 60.6^{\circ}C$	$P_{ch(max)} = 150 W$ , $T_c = 110.6^{\circ}C$
D1 D15XB60 SHINDENGEN	$T_{jmax} = 150^{\circ}C$ , $P_d = 5.17 W$ , $T_j = T_c + ((\theta_{j-c}) \times P_d) = 114.0^{\circ}C$ $D.F. = 76.0\%$	$\theta_{j-c} = 1.5^{\circ}C/W$ , $\Delta T_c = 56.2^{\circ}C$	$T_c = 106.2^{\circ}C$
D2 10JL2CZ47A TOSHIBA	$T_{jmax} = 150^{\circ}C$ , $P_d = 3.28 W$ , $T_j = T_c + ((\theta_{j-c}) \times P_d) = 109.9^{\circ}C$ $D.F. = 73.3\%$	$\theta_{j-c} = 3.6^{\circ}C/W$ , $\Delta T_c = 48.1^{\circ}C$	$T_c = 98.1^{\circ}C$
D51 ESAD92M-02R FUJI-ELE.	$T_{jmax} = 150^{\circ}C$ , $P_d = 9.50 W$ , $T_j = T_c + ((\theta_{j-c}) \times P_d) = 131.4^{\circ}C$ $D.F. = 87.6\%$	$\theta_{j-c} = 2.0^{\circ}C/W$ , $\Delta T_c = 62.4^{\circ}C$	$T_c = 112.4^{\circ}C$
Q101 2SC2712-Y -TE85L TOSHIBA	$T_{jmax} = 125^{\circ}C$ , $P_d = 1 mW$ , $T_j = T_a + ((\theta_{j-a}) \times P_d) = 80.2^{\circ}C$ $D.F. = 64.2\%$	$\theta_{j-a} = 667^{\circ}C/W$ , $\Delta T_a = 29.5^{\circ}C$	$P_{c(max)} = 150 mW$ , $T_a = 79.5^{\circ}C$
Q102 2SK2177-4061 SHINDENGEN	$T_{chmax} = 150^{\circ}C$ , $P_d = 25 mW$ , $T_{ch} = T_c + ((\theta_{ch-c}) \times P_d) = 74.6^{\circ}C$ $D.F. = 49.7\%$	$\theta_{ch-c} = 12.5^{\circ}C/W$ , $\Delta T_c = 24.3^{\circ}C$	$P_{ch(max)} = 10 W$ , $T_c = 74.3^{\circ}C$
Q201 2SC2712-Y -TE85L TOSHIBA	$T_{jmax} = 125^{\circ}C$ , $P_d = 1 mW$ , $T_j = T_a + ((\theta_{j-a}) \times P_d) = 83.2^{\circ}C$ $D.F. = 66.6\%$	$\theta_{j-a} = 667^{\circ}C/W$ , $\Delta T_a = 32.5^{\circ}C$	$P_{c(max)} = 150 mW$ , $T_a = 82.5^{\circ}C$
PC101 PS2581L2-E3(D) (LED) NEC	$T_{jmax} = 125^{\circ}C$ , $I_d = 0 mA$ , ALLOWABLE $I_p(max) = 53.4mA$ (at $T_a = 83.7^{\circ}C$ ) $D.F. = 0\%$	$\theta_{j-a} = 667^{\circ}C/W$ , $\Delta T_a = 33.7^{\circ}C$	$P_{d(max)} = 150 mW$ , $T_a = 83.7^{\circ}C$
PC101 PS2581L2-E3(D) (Transistor) NEC	$T_{jmax} = 125^{\circ}C$ , $P_d = 0 mW$ , $T_j = T_a + ((\theta_{j-a}) \times P_d) = 83.7^{\circ}C$ $D.F. = 67.0\%$	$\theta_{j-a} = 667^{\circ}C/W$ , $\Delta T_a = 33.7^{\circ}C$	$P_{c(max)} = 150 mW$ , $T_a = 83.7^{\circ}C$
PC102 PS2581L2-E3(D) (LED) NEC	$T_{jmax} = 125^{\circ}C$ , $I_d = 1.2 mA$ , ALLOWABLE $I_p(max) = 53.4mA$ (at $T_a = 85.8^{\circ}C$ ) $D.F. = 2.2\%$	$\theta_{j-a} = 667^{\circ}C/W$ , $\Delta T_a = 35.8^{\circ}C$	$P_{d(max)} = 150 mW$ , $T_a = 85.8^{\circ}C$
PC102 PS2581L2-E3(D) (Transistor) NEC	$T_{jmax} = 125^{\circ}C$ , $P_d = 25 mW$ , $T_j = T_a + ((\theta_{j-a}) \times P_d) = 102.5^{\circ}C$ $D.F. = 82.0\%$	$\theta_{j-a} = 667^{\circ}C/W$ , $\Delta T_a = 35.8^{\circ}C$	$P_{c(max)} = 150 mW$ , $T_a = 85.8^{\circ}C$
A101 FA5502M-TE1 FUJI-ELE.	$T_{jmax} = 150^{\circ}C$ , $P_d = 90.0 mW$ , $T_j = T_c + ((\theta_{j-c}) \times P_d) = 94.2^{\circ}C$ $D.F. = 62.8\%$	$\theta_{j-c} = 50^{\circ}C/W$ , $\Delta T_c = 39.7^{\circ}C$	$P_{d(max)} = 650 mW$ , $T_c = 89.7^{\circ}C$
A102 M51995AFP-600C MITSUBISHI	$T_{jmax} = 150^{\circ}C$ , $P_d = 297 mW$ , $T_j = T_c + ((\theta_{j-c}) \times P_d) = 120.3^{\circ}C$ $D.F. = 80.2\%$	$\theta_{j-c} = 40^{\circ}C/W$ , $\Delta T_c = 58.4^{\circ}C$	$P_{d(max)} = 1.5 W$ , $T_c = 108.4^{\circ}C$
D101, D102 D1FL20U-4063 SHINDENGEN	$T_{jmax} = 150^{\circ}C$ , $P_d = 0 W$ , $T_j = T_a + ((\theta_{j-a}) \times P_d) = 78.2^{\circ}C$ $D.F. = 52.1\%$	$\theta_{j-a} = 108^{\circ}C/W$ , $\Delta T_a = 28.2^{\circ}C$	$T_a = 78.2^{\circ}C$

Location No.	Vin = 100VAC	Load = 100%	Ta = 50°C
D103 D1FL20U-4063 SHINDENGEN	Tjmax = 150 °C, Pd = 0 mW, Tj = Ta + ((θ j-a) × Pd) = 91.6 °C D.F. = 61.0%	θ j-a = 108 °C/W, Δ Ta = 41.6 °C, Tj = Ta + ((θ j-a) × Pd) = 91.6 °C	Ta = 91.6 °C
D104 CRH01-TE85L TOSHIBA	Tjmax = 150 °C, Pd = 19.6 mW, Tj = Ta + ((θ j-a) × Pd) = 93.2 °C D.F. = 62.2%	θ j-a = 130 °C/W, Δ Ta = 40.7 °C, Tj = Ta + ((θ j-a) × Pd) = 93.2 °C	Ta = 90.7 °C
D105 CRH01-TE85L TOSHIBA	Tjmax = 150 °C, Pd = 8.1 mW, Tj = Ta + ((θ j-a) × Pd) = 94.1 °C D.F. = 62.7%	θ j-a = 130 °C/W, Δ Ta = 43.0 °C, Tj = Ta + ((θ j-a) × Pd) = 94.1 °C	Ta = 93.0 °C
D106 CRH01-TE85L TOSHIBA	Tjmax = 150 °C, Pd = 40 mW, Tj = Ta + ((θ j-a) × Pd) = 103.3 °C D.F. = 68.9%	θ j-a = 130 °C/W, Δ Ta = 48.1 °C, Tj = Ta + ((θ j-a) × Pd) = 103.3 °C	Ta = 98.1 °C
D201 CRH01-TE85L TOSHIBA	Tjmax = 150 °C, Pd = 10 mW, Tj = Ta + ((θ j-a) × Pd) = 85.3 °C D.F. = 56.9%	θ j-a = 130 °C/W, Δ Ta = 34.0 °C, Tj = Ta + ((θ j-a) × Pd) = 85.3 °C	Ta = 84.0 °C
D202 ISS184-TE85L TOSHIBA	Tjmax = 125 °C, Pd = 0 mW, Tj = Ta + ((θ j-a) × Pd) = 87.4 °C D.F. = 69.9%	θ j-a = 667 °C/W, Δ Ta = 37.4 °C, Tj = Ta + ((θ j-a) × Pd) = 87.4 °C	P(max) = 150 mW Ta = 87.4 °C
Z101 U1ZB27-TE12L TOSHIBA	Tjmax = 150 °C, Pd = 0 mW, Tj = Ta + ((θ j-a) × Pd) = 83.8 °C D.F. = 55.9%	θ j-a = 125 °C/W, Δ Ta = 33.8 °C, Tj = Ta + ((θ j-a) × Pd) = 83.8 °C	P(max) = 1.0 W Ta = 83.8 °C
Z102 U1ZB27-TE12L TOSHIBA	Tjmax = 150 °C, Pd = 0 mW, Tj = Ta + ((θ j-a) × Pd) = 89.4 °C D.F. = 59.6%	θ j-a = 125 °C/W, Δ Ta = 39.4 °C, Tj = Ta + ((θ j-a) × Pd) = 89.4 °C	P(max) = 1.0 W Ta = 89.4 °C
Z104 02CZ15-Y-TE85L TOSHIBA	Tjmax = 150 °C, Pd = 25 mW, Tj = Ta + ((θ j-a) × Pd) = 102.2 °C D.F. = 68.1%	θ j-a = 625 °C/W, Δ Ta = 36.6 °C, Tj = Ta + ((θ j-a) × Pd) = 102.2 °C	Pd(max) = 200 mW Ta = 86.6 °C
Z105 02CZ11-X-TE85L TOSHIBA	Tjmax = 150 °C, Pd = 0 mW, Tj = Ta + ((θ j-a) × Pd) = 83.8 °C D.F. = 55.9%	θ j-a = 625 °C/W, Δ Ta = 33.8 °C, Tj = Ta + ((θ j-a) × Pd) = 83.8 °C	Pd(max) = 200 mW Ta = 83.8 °C
Z201 MA3330-L-TX MATSUSHITA	Tjmax = 150 °C, Pd = 0 mW, Tj = Ta + ((θ j-a) × Pd) = 93.6 °C D.F. = 62.4%	θ j-a = 625 °C/W, Δ Ta = 43.6 °C, Tj = Ta + ((θ j-a) × Pd) = 93.6 °C	Pd(max) = 200 mW Ta = 93.6 °C
Z202 02CZ18-Y-TE85L TOSHIBA	Tjmax = 150 °C, Pd = 36 mW, Tj = Ta + ((θ j-a) × Pd) = 108.1 °C D.F. = 72.1%	θ j-a = 625 °C/W, Δ Ta = 35.6 °C, Tj = Ta + ((θ j-a) × Pd) = 108.1 °C	Pd(max) = 200 mW Ta = 85.6 °C
A201 μPC1093-E1 NEC	Tjmax = 150 °C, Pd = 30 mW, Tj = Ta + ((θ j-a) × Pd) = 108.9 °C D.F. = 72.6 %	θ j-a = 315 °C/W, Δ Ta = 49.4 °C, Tj = Ta + ((θ j-a) × Pd) = 108.9 °C	Pd(max) = 400 mW Ta = 99.4 °C

3. MAIN COMPONENTS TEMPERATURE RISE  $\Delta T$  LIST

MODEL : DLP240-24-1

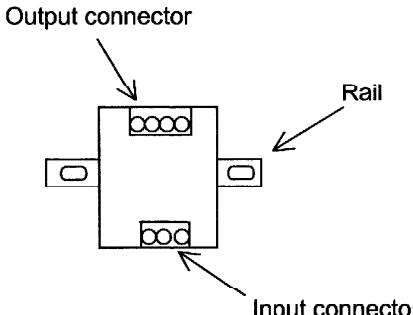
Measuring Conditions

Mounting Method (Standard Mounting)		
	Input Voltage (VAC)	100
	Output Voltage (VDC)	24
	Output Current (A)	10.0

※ Condition  $T_a = 50^{\circ}\text{C}$ , Convection cooling .

Output Derating (100%) $T_a = 50^{\circ}\text{C}$		Standard Mounting
Location No.	Parts Name	$\Delta T$ Temperature rise ( $^{\circ}\text{C}$ )
L1	BALUN COIL	50.3
L2	BALUN COIL	43.7
L3	CHOKE COIL	41.6
D1	BRIDGE DIODE	56.2
D2	FRD	48.1
Q1	MOS FET	58.6
Q2	MOS FET	60.6
D51	LLD	62.4
T1	TRANS PULSE	52.6
L55	CHOKE COIL	67.7
A101	CHIP IC	39.7
A102	CHIP IC	58.4
C6	E. CAP.	26.9
C9	E. CAP.	28.6
C10	E. CAP.	37.5
C51	E. CAP.	34.6
C52	E. CAP.	36.6
C53	E. CAP.	37.2
C57	E. CAP.	41.5

## Measuring Conditions

Mounting Method (Standard Mounting)		
	Input Voltage (VAC)	230
	Output Voltage (VDC)	24
	Output Current (A)	10.0

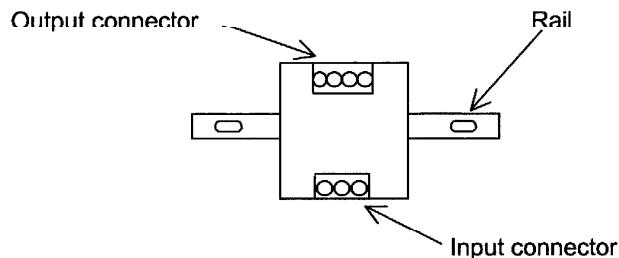
※ Condition Ta = 50°C , Convection cooling .

Output Derating (100%) Ta = 50°C		Standard Mounting
Location No.	Parts Name	ΔT Temperature rise (°C)
L1	BALUN COIL	26.5
L2	BALUN COIL	23.1
L3	CHOKE COIL	33.8
D1	BRIDGE DIODE	36.4
D2	FRD	33.3
Q1	MOS FET	35.8
Q2	MOS FET	45.1
D51	LLD	56.6
T1	TRANS PULSE	50.2
L55	CHOKE COIL	67.4
A101	CHIP IC	38.5
A102	CHIP IC	57.4
C6	E. CAP.	23.1
C9	E. CAP.	26.1
C10	E. CAP.	32.9
C51	E. CAP.	26.5
C52	E. CAP.	27.8
C53	E. CAP.	27.9
C57	E. CAP.	37.9

## 4. ELECTROLYTIC CAPACITOR LIFETIME

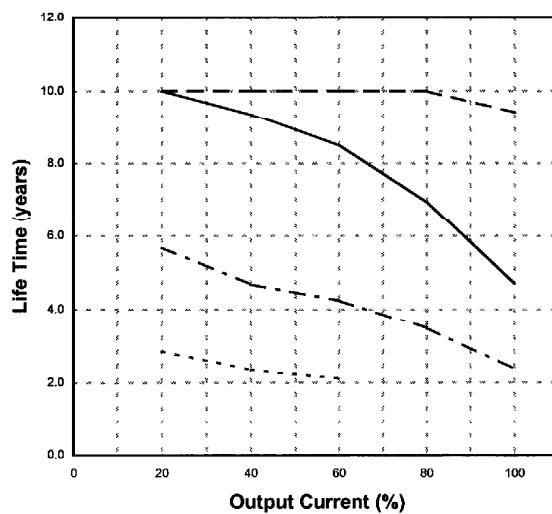
MODEL: DLP240-24-1

STANDARD MOUNTING



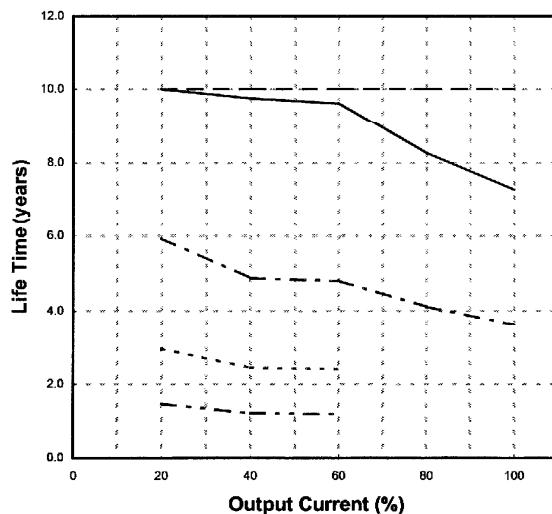
Vin = 100VAC

Load (%)	Life Time (years)			
	Ta = 30°C	Ta = 40°C	Ta = 50°C	Ta = 60°C
20	10.0	10.0	5.7	2.8
40	10.0	9.4	4.7	2.3
60	10.0	8.5	4.2	2.1
80	10.0	7.0	3.5	---
100	9.4	4.7	2.4	---



Vin = 230VAC

Load (%)	Life Time (years)				
	Ta = 30°C	Ta = 40°C	Ta = 50°C	Ta = 60°C	Ta = 70°C
20	10.0	10.0	5.9	3.0	1.5
40	10.0	9.8	4.9	2.4	1.2
60	10.0	9.6	4.8	2.4	1.2
80	10.0	8.3	4.1	2.1	---
100	10.0	7.3	3.6	---	---



Ta = 30°C -----  
 Ta = 40°C -----  
 Ta = 50°C -----  
 Ta = 60°C -----  
 Ta = 70°C -----

Ta = 40°C -----  
 Ta = 50°C -----  
 Ta = 60°C -----

## 5. ABNORMAL TEST

MODEL : DLP240-24-1

## (1) Conditions

Input : 230VAC

Output : 24V / 10A

Ta : 25°C , 70%RH

## (2) Test Results

(Da : Damaged)

No.	Test position		Test Mode		Test Results												Note
	Location No.	Test Point	Short Open	Fire	Smoke	Burst	Smell	Red Hot	Damaged	Fuse Blown	OVF	OCP	No Output	No Change	Others		
1	Q1	D-G	O						O O			O					Da:Z101
2		D-S	O						O			O					
3		G-S	O											O			Input Power Increase(8W)
4		D	O										O				
5		S	O										O				Input Power Increase(8W)
6		G	O						O O			O					Da:Q1
7	Q2	D-G	O						O O			O					Da:Z102
8		D-S	O						O O			O					Da:D103,R171,R172
9		G-S	O									O					
10		D	O									O					
11		S	O									O					
12		G	O						O O			O					Da :D103,Q2,R171,R172
13	D1	AC-AC	O						O O			O					Da :TH1,TH2
14		AC-DC	O						O			O					
15		AC	O									O					
16		DC	O									O					
17	D2		O						O O			O					Da : Q1
18			O						O O			O					Da : Q1
19	D51	K-A1	O									O					
20		K-A2	O									O					
21		K	O									O					
22		A1	O									O					
23		A2	O						O O			O					Da :D103,Q2,R171,R172
24	C6		O						O			O					
25			O						O O			O					Da:Q1
26	C51		O									O O					
27			O									O					Output Ripple Increase

No.	Test position		Test Mode		Test Results												Note
	Location No.	Test Point	Short	Open	1	2	3	4	5	6	7	8	9	10	11	12	
					Fire	Smoke	Burst	Smell	Red Hot	Damaged	Fuse Blown	OVP	OCP	No Output	No Change	Others	
28	L3	1-2	O												O		
29		7,8-5,6	O							O	O			O		Da : Q1	
30		5,6	O											O			
31		1	O											O			
32		2	O											O			
33	L55		O												O	Output Voltage Low	
34			O											O			
35	T1	1-2	O											O			
36		2-6	O							O	O			O		Da : D103,R171,R172	
37		6-8	O											O			
38		9-10	O									O		O	Output Voltage Low		
39		10-13	O											O	Output Voltage Low		
40		13-16	O									O					
41		1	O											O	Output Voltage Low		
42		6	O									O					
43		8	O									O					
44	D104		O											O	Input Power Increase(8W)		
45			O											O	Input Power Increase (4W)		
46	D105		O											O	Input Power Increase (5W)		
47			O											O	Input Power Increase (4W)		
48	D106		O									O					
49			O											O	Output Voltage Unstable(3V)		
50	R112		O											O			
51			O											O			
52			O											O			
53	R117		O						O	O			O		Da :D103,Q2,R171,R172		
54		1-2	O											O			
55	PC101	3-4	O								O	O					
56		1,2	O											O			
57		3,4	O											O			
58		1-2	O								O	O					
59	PC102	3-4	O									O					
60		1,2	O								O	O					
61		3,4	O								O	O					

**6. VIBRATION TEST****MODEL : DLP240-24-1****(1) Vibration Test Class**

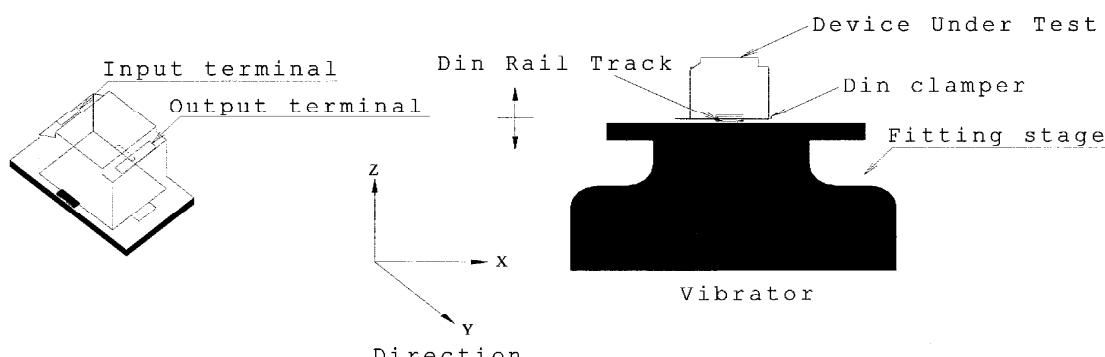
Frequency Variable Endurance Test

**(2) Equipment Used**

- Controller : DP550 (DP CORP. USA)
- Vibrator : V870 (LDS CORP. UK)

**(3) Test Conditions**

- Sweep frequency      10 ~ 55Hz
- Sweep time            1.0 min.
- Acceleration          Constant  $9.8\text{m/s}^2$  ( 1G )
- Direction             X, Y, Z.
- Test time             1 hour each

**(4) Test Method****(5) Test Results****O K**

Vin : 100VAC

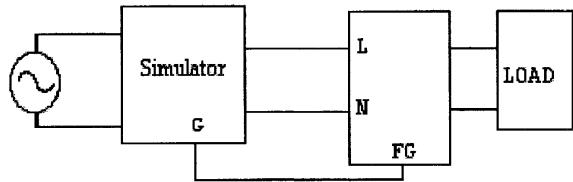
Iout : 100%

Check item	Output Voltage (V)		Ripple Voltage (mVp-p)	D.U.T.State
Before Test	24.000		55	_____
After Test	X	24.006	50	O.K.
	Y	24.006	50	O.K.
	Z	24.007	50	O.K.

## **7. NOISE SIMULATE TEST**

**MODEL : DLP240-24-1**

### **(1) Test Circuit And Equipment**



Simulator : INS-400L      Noise Laboratory Co.,LTD

### **(2) Test Conditions**

- |                       |   |               |               |   |                  |
|-----------------------|---|---------------|---------------|---|------------------|
| • Input Voltage       | : | 100, 230VAC   | • Noise Level | : | 0V~2kV           |
| • Output Voltage      | : | Rated         | • Phase Shift | : | 0° ~ 360°        |
| • Output Current      | : | 0%, 100%      | • Polarity    | : | +, -             |
| • Ambient Temperature | : | 25°C          | • Mode        | : | Normal<br>Common |
| • Pulse Width         | : | 50ns ~ 1000ns | • Trig Select | : | Line             |

### **(3) Acceptable Conditions**

1. Not to be broken.
2. Not to be shut down output.
3. No other out of orders.

### **(4) Test Result**

**O K**

## 8. THERMAL SHOCK TEST

**MODEL : DLP240-24-1**

**(1) Equipment Used**

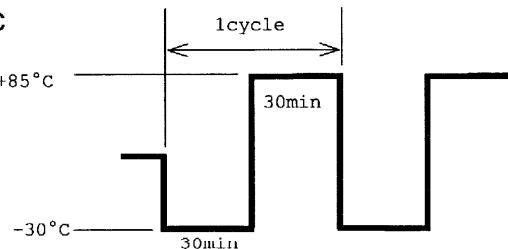
THERMAL SHOCK CHAMBER TSV-40 (TABAI ESPEC CORP.)

**(2) The Number of D.U.T.(Device Under Test)**

2 units

**(3) Test Conditions**

- Ambient Temperature : -30°C  $\longleftrightarrow$  85°C
- Test Time : Refer to drawing +85°C
- Test Cycle : 100 Cycles
- Not Operating



**(4) Test Method**

Before testing, check if there is no abnormal output, then put the D.U.T. in testing chamber, and test it according to the above cycle. 100 cycles later, leave it for 1 hour at the room temperature, then check if there is no abnormal output.

**(5) Test Results**

OK

Vin : 100VAC		24V						
Io : 100%		FROM			TO			
Ripple Noise	mV	65		16				
Spike Noise	mV	70		80				
Line Regulation	MIN MAX	V V	23.975 23.975	0mV	23.989 23.990	1mV		
Load Regulation	0% 100%	V V	24.011 23.975	36mV	24.019 23.989	30mV		
Efficiency	Pin Vout Iout	W V A	290.6 23.975 10	82.5%	288.0 23.989 10	83.3%		
Solder Condition • etc.			—		OK			